

JP6069280A 19940311 FullText

Title: (ENG) MOUNTING STRUCTURE FOR BARE CHIP

Abstract: (ENG)

PURPOSE: To facilitate removal of a bare chip by curing an insulating layer for fixing the chip to a predetermined surface of a board by heating, and further forming it of a synthetic resin material to be softened by heating it to a temperature higher than the predetermined temperature.

CONSTITUTION: The mounting structure for a bare chip comprises a board 8 having pads 3 to be connected to connecting parts 2 through a leader pattern 9 and formed at predetermined surface 1A of an insulating member 1, a bare chip 4 having electrodes 5, and bumps 7 for connecting the pads 3 to the electrodes 5. The chip 4 is fixed to the surface 1A through an insulating layer 6, and the electrodes 5 are so connected as to have conduction with the parts 2. In such a mounting structure of the chip 4, the layer 6 is so cured by heating it to a predetermined temperature T1 as to remove the chip 4 from the board 8 as required and formed of synthetic resin to be softened by heating to a temperature T2 higher than the temperature T1.

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Patents Citing This One (3):

US6316528B1

20011113 LOCTITE R & D LTD US

Thermosetting resin compositions

US6274389B1

20010814 LOCTITE R & D LTD US; MATSUSHITA ELECTRIC IND CO LTD US; LOCTITE CORP US

Mounting structure and mounting process from semiconductor devices

US5427511A

19950627 COPELAND CORP US

Scroll compressor having a partition defining a discharge chamber